



S&amp;H Form: (02/05)

## REPLY/AMENDMENT FEE TRANSMITTAL

		Attorney Docket No.	1572.1194	
		Application Number	10/706,033	
		Filing Date	November 13, 2003	
		First Named Inventor	Se-young JANG	
		Group Art Unit	1756	
AMOUNT ENCLOSED	0.00	Examiner Name	Nicole M. Barreca	

### FEE CALCULATION (fees effective 12/08/04)

CLAIMS AS AMENDED	Claims Remaining After Amendment	Highest Number Previously Paid For	Number Extra	Rate	Calculations
TOTAL CLAIMS	11	- 20 =	0	X \$ 50.00 =	\$ 0.00
INDEPENDENT CLAIMS	2	- 3 =	0	X \$ 200.00 =	0.00
Since an Official Action set an <u>original</u> due date of <u>September 29, 2005</u> , petition is hereby made for an extension to cover the date this reply is filed for which the requisite fee is enclosed (1 month (\$120)); (2 months (\$450)); (3 months (\$1,020)); (4 months (\$1,590)); (5 months (\$2,160)).					
If Notice of Appeal is enclosed, add (\$500.00)					
If Statutory Disclaimer under Rule 20(d) is enclosed, add fee (\$130.00)					
Information Disclosure Statement (Rule 1.17(p)) (\$180.00)					
Total of above Calculations =					
Reduction by 50% for filing by small entity (37 CFR 1.9, 1.27 & 1.28)					
<b>TOTAL FEES DUE =</b>					

- (1) If entry (1) is less than entry (2), entry (3) is "0".
- (2) If entry (2) is less than 20, change entry (2) to "20".
- (4) If entry (4) is less than entry (5), entry (6) is "0".
- (5) If entry (5) is less than 3, change entry (5) to "3".

### METHOD OF PAYMENT

- Check enclosed as payment.
- Charge "TOTAL FEES DUE" to the Deposit Account No. below.
- No payment is enclosed.

### GENERAL AUTHORIZATION

- If the above-noted "AMOUNT ENCLOSED" is not correct, the Commissioner is hereby authorized to credit any overpayment or charge any additional fees necessary to:
 

Deposit Account No.	19-3935
Deposit Account Name	STAAS & HALSEY LLP
- The Commissioner is also authorized to credit any overpayments or charge any additional fees required under 37 CFR 1.16 (filing fees) or 37 CFR 1.17 (processing fees) during the prosecution of this application, including any related application(s) claiming benefit hereof pursuant to 35 USC § 120 (e.g., continuations/divisionals/CIPs under 37 CFR 1.53(b) and/or continuations/divisionals/CPAs under 37 CFR 1.53(d)) to maintain pendency hereof or of any such related application.

SUBMITTED BY: STAAS &amp; HALSEY LLP

Typed Name	Uchendu O. Anyaso	Reg. No.	51,411	
Signature			Date	January 12, 2006



STFW

Docket No.: 1572.1194

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Se-young JANG

Serial No. 10/706,033

Group Art Unit: 1756

Confirmation No. 6029

Filed: November 13, 2003

Examiner: Nicole M. Barreca

For: METHOD OF FABRICATING LEAD-FREE SOLDER BUMPS

**SUPPLEMENTAL AMENDMENT**

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

This Supplemental Amendment is in response to the Notice of Non-Compliant  
Amendment (37 CFR 1.121) mailed December 22, 2005.

Reconsideration of the claims is respectfully requested. The following remarks are  
respectfully submitted.